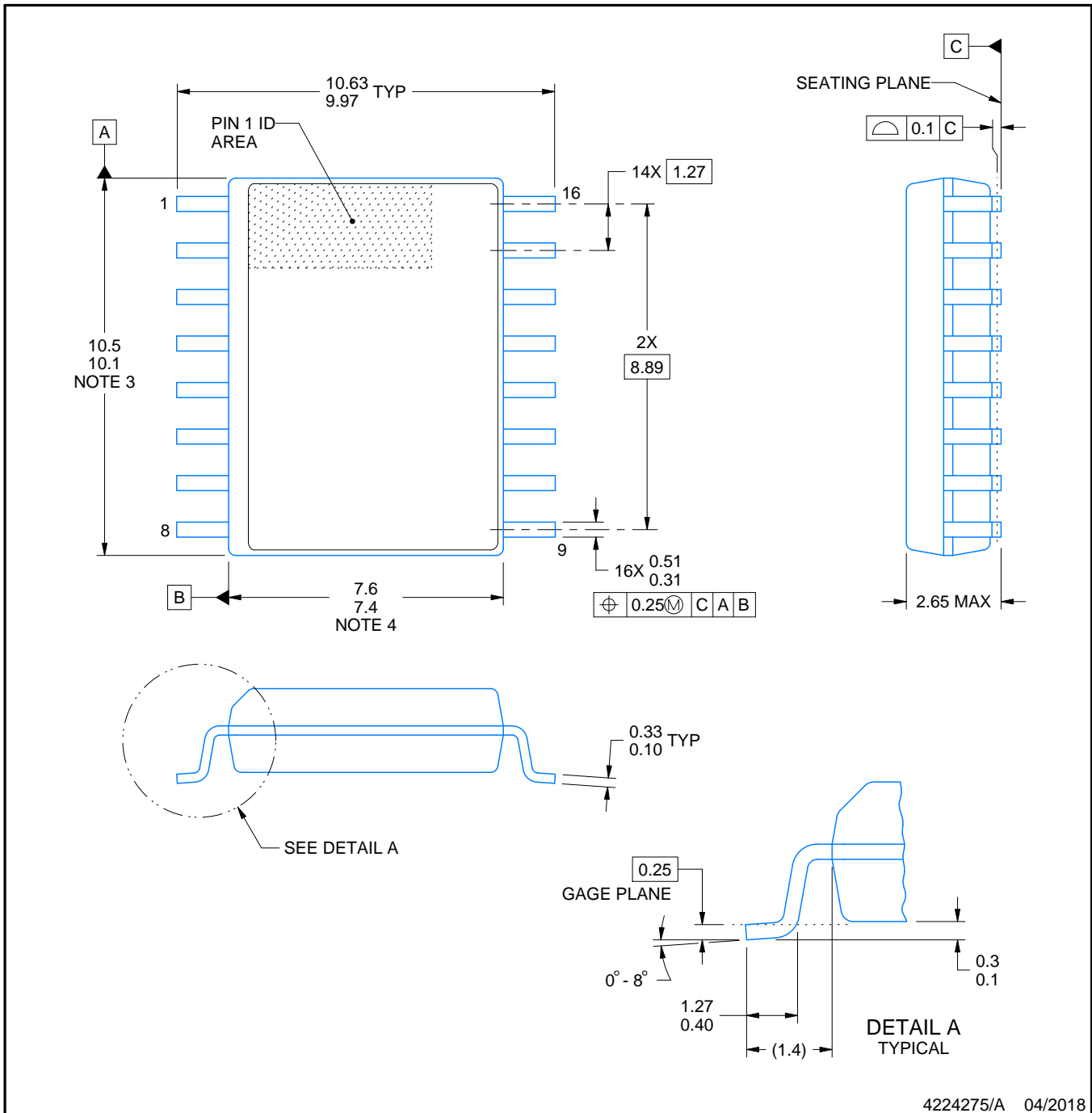


PACKAGE OUTLINE

DVE0016A

SO-MOD - 2.65 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



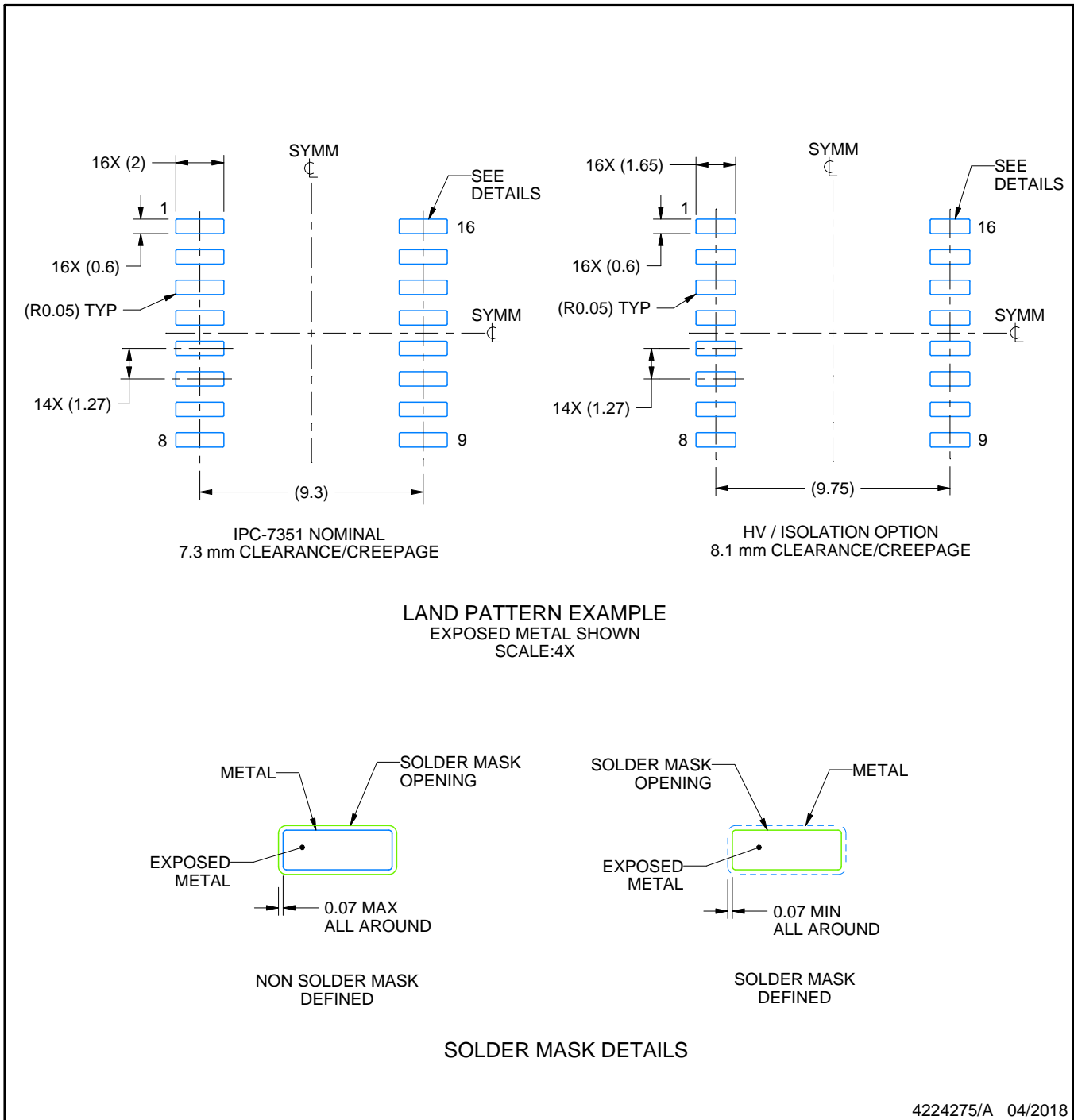
4224275/A 04/2018

EXAMPLE BOARD LAYOUT

DVE0016A

SO-MOD - 2.65 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

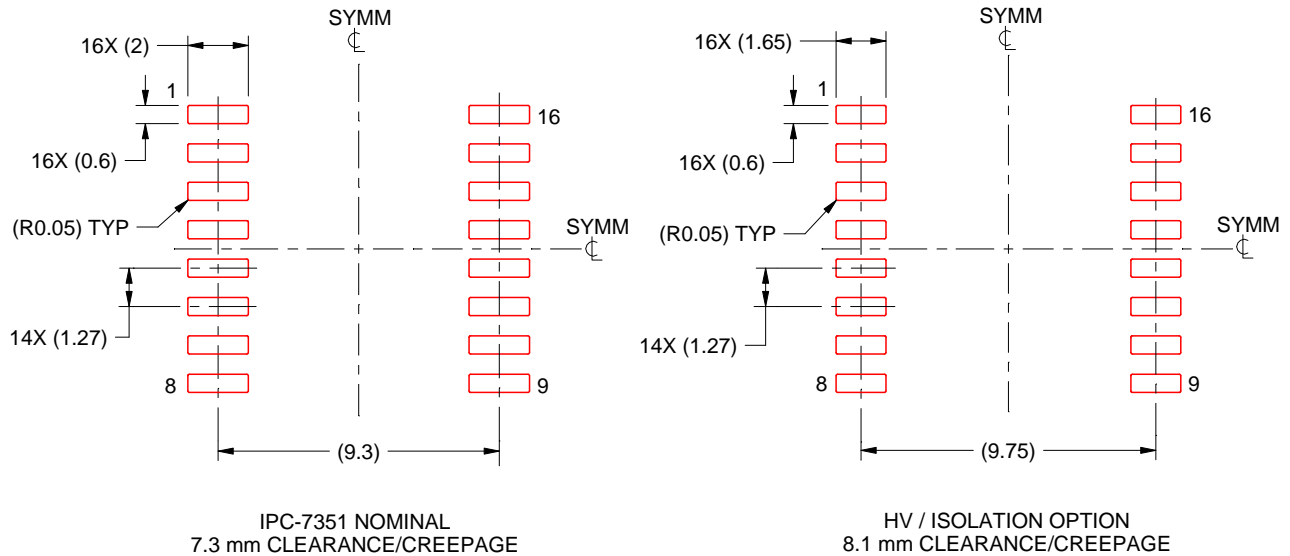
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DVE0016A

SO-MOD - 2.65 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:4X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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